

SID

Factory: Rot am See

Article:

591

ML10

Provided:

Landwehr, Melanie

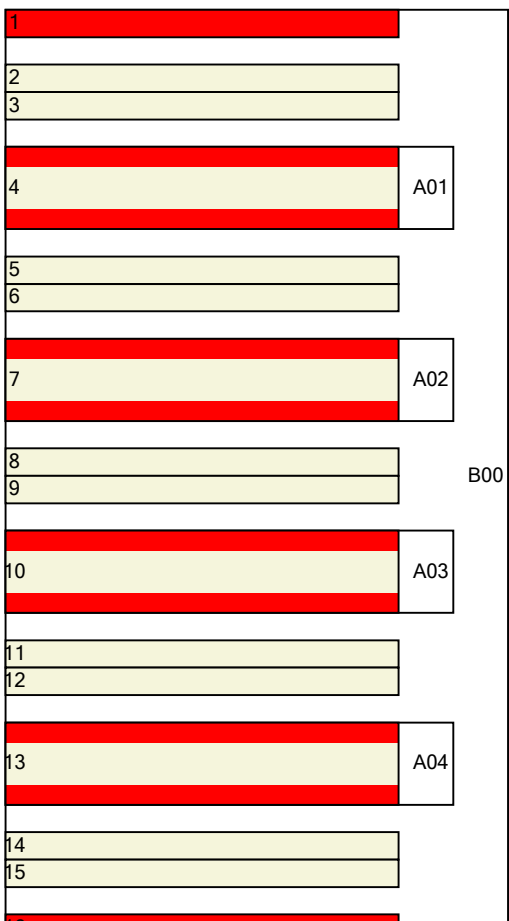
Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	165		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		
		35	L2	
A-RS-FR4-ML-0.20mm-035+035-TG150-HF	50200653	200	L3	
		35		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	110		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		
		35	L4	
A-RS-FR4-ML-0.20mm-035+035-TG150-HF	50200653	200	L5	
		35		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	195		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		
		35	L6	
A-RS-FR4-ML-0.20mm-035+035-TG150-HF	50200653	200	L7	
		35		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	110		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		
		35	L8	
A-RS-FR4-ML-0.20mm-035+035-TG150-HF	50200653	200	L9	
		35		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	165		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1861 µm

Version 1.2.14.15

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